# Silicon Wafer Japan TC Chapter

Japan Standards Spring Meetings 2024
Friday, April 26, 2024
Official Virtual TC Chapter Meeting
10:00-12:00 JST

# AGENDA

## 1 Welcome/Call to Order

1.1 Introductions

1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)

1.3 Agenda Review

## 2 Review of Previous Meeting Minutes

## 3 Liaison Report

3.1 JRSC Report

3.2 GCS Report

3.3 Europe TC Chapter

3.4 North America TC Chapter

## 4 Staff Report

## 5 Ballot Review

None

## 6 Subcommittee & Task Force Reports

6.1 International Advanced Wafer Geometry Task Force

6.2 International/ Japan Test Method Task Force

6.3 International Advanced Surface Inspection Task Force

6.4 International Polished Wafers Task Force

6.5 International Epitaxial Wafers Task Force

6.6 International Annealed Wafers Task Force

6.7 International SOI Wafers Task Force

6.8 International Terminology Task Force

## 7 Old Business

7.1 Project Period Review

7.2 5-year Review

- SEMI M88-0119, Practice for Sample Preparation Methods for Measuring Minority Carrier Diffusion Length in Silicon Wafers by Surface Photovoltage Methods
- SEMI M85-0120, Guide for the Measurement of Trace Metal Contamination on Silicon Wafer Surface by Inductively Coupled Plasma Mass Spectrometry

## 8 New Business

## 9 Action Item Review

9.1 Open Action Items

| *Item #* | *Assigned to* | *Details* |
|---|---|---|
| SW20231214-01 | Test Method TF | To review the contents of SMI M88 to decide whether it is reapproval ballot by next TC Chapter meeting. |
| SW20231214-02 | Tetsuya Nakai (SUMCO) | To inform the proposal and ask each TF leaders regarding M52 and M73 to proceed the action. |

9.2 New Action Items

| *Item #* | *Assigned to* | *Details* |
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## 10 Next Meeting and Adjournment

10.1 The next meeting is scheduled for <date> at <event/location>.